EXHAUST GAS TREATMENT PRODUCTS

Discover the Advantages
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DISCOVER THE ADVANTAGES

As an internationally operating company with a global network of service centers, CS CLEAN SYSTEMS has been serving customers in the semiconductor and related high tech industries since 1986. Based on our proprietary dry bed absorption technology, our products have earned an unparalleled track record for safety, process reliability and environmentally-sustainable manufacturing.

Whether your work relates to semiconductors, photovoltaics, pharmaceuticals or chemicals, on an R&D or manufacturing scale, if your application requires removal of downstream reactive gases please contact us and discover the advantages of CS CLEAN SYSTEMS unique technology and worldwide support!
CS CLEAN SYSTEMS gas abatement products are unmatched in their scrubbing efficiency, yet easy to operate and extremely maintenance-friendly.

The schematic shows an overview of the various product lines as installed on the gas supply and process exhaust of a typical semiconductor wafer manufacturing fab. Refer to the following pages for a further description of the various product lines.

We need your input! Perhaps your machine has a small volume of concentrated gas which requires periodic venting. Or, maybe you already have a CLEANSORB system installed on a plasma etch application and intend to add a further gas to the etch recipe.

No problem: simply contact us and provide us with the details! To specify a CLEANSORB model and configuration best suited to your scrubbing requirements, we need to understand more about the type of gases to be removed, carrier gas flow, inert gas contribution of pumps, etc. Your local sales and service partner will be pleased to provide you with a Process Definition Sheet for this purpose.
CLEANSORB® TECHNOLOGY

CLEANSORB dry chemisorber media removes hazardous process gases by chemical conversion to stable solids at ambient temperature. It is the enabling technology for the CS CLEAN SYSTEMS line of dry scrubbing products. No external heating, moisturization, or other facilities are required for operation. Hence the CLEANSORB system is fully passive, and is permanently on stand-by, even in the event of a power outage or other facilities failure.

Where scrubbing performance is expressed in terms of “percent waste gas removal”, the non-retained percentage of gas is often enough to cause considerable corrosion or blockage of downstream ducting and equipment.

CS CLEAN SYSTEMS specifies retention efficiency of its dry bed columns as absolute ppm concentrations. Gas concentration at the CLEANSORB column’s outlet typically lies below the detection level of commonly used gas detectors- right up until the end of absorber capacity lifetime.

CS CLEAN SYSTEMS has a dedicated team of R&D chemists focussed on developing its range of CLEANSORB granulates.

Our chemisorber materials are developed “from scratch” in our laboratory and scaled up to the bulk manufacturing level. Ongoing review and testing ensures that our media keeps pace with the latest manufacturing technologies and process chemistries.

Benefits
- Safe, non-combustible inorganic medium (no charcoal)
- Highest capacities
- Unique customised material compositions
- No consumption of electricity, city water, oxygen, nitrogen
- No secondary emissions to the environment
- Excellent Cost-of-Ownership
- Irreversible conversion of hazardous gases to stable inorganic solids at ambient temperature
CLEAN, SAFE, EXHAUST GAS ABATEMENT

Many of the specialty process gases used in semiconductor wafer manufacturing and related high-tech industries are either pyrophoric, toxic, or corrosive. Unused process gases and their hazardous by-products must be efficiently and safely removed from exhaust lines to ensure safety of personnel, compliance with regulatory emission standards, and process uptime.

Increasing levels of device integration and shrinking critical dimensions require new materials for the deposition of inter-level metal connectors, barrier-, and dielectric layers. Increasingly, these are complex metalorganic molecules supplied from liquid sources. Over the years, CS CLEAN SYSTEMS has gained extensive experience in the abatement of MO precursors through its exposure to compound semiconductor and ALD applications. Point-of-use CLEANSORB models are available to meet the needs of all our customers, from small-scale university researchers to round-the-clock fabrication.

CLEANSORB® COLUMNS

The CLEANSORB absorber column has been specially designed with handling and refilling logistics in mind. The dry scrubbing columns are approved as container vessels for road transport of the spent absorber material in accordance with applicable ADR/ DOT regulations. CLEANSORB columns are not discarded after use, but refilled with fresh absorbent.

The columns are manufactured from high quality 316L stainless steel to ensure long working life, even on harsh process applications such as Metal Etching or Tungsten CVD. The inlet and outlet connections to the patented CLEANSORB absorber column are made via its own integrated valves. Before taking a column off-line, the valves are shut off to isolate the absorber bed and any process deposits - ensuring maximum safety and ease of handling for the operator.

Benefits
- Reusable
- UN-approved for transportation
- Local disposal service worldwide
- Maximum operational safety
- No exposure to chemicals
- Hermetically sealed modules

Benefits
- No consumption of water resources
- No generation of waste water
- No secondary emissions
- Room temperature operation
- No pressure drop over column lifetime
- Safety bypass
- Outlet concentrations can be monitored as absolute, TLV-level concentrations
- Passive operating principle
- Applicable to a wide range of hazardous gases
Even when working in high volume production, the maintenance-friendly CLEANSORB dry bed absorber rarely requires intervention from factory service technicians. There are no moving parts or heated components which require frequent attention, or scrubber parts which require regular cleaning. Most typically, service work is limited to change-out of the column, periodic calibration of the endpoint (gas) sensor, and annual preventive replacement of inlet steel bellows and O-rings.

CLEANSORB customers enjoy a comprehensive maintenance package comprising a unique take-back and disposal service for the spent absorber media. After removal from the CLEANSORB cabinet, the column is ready for shipment to the nearest CS CLEAN SYSTEMS Refill and Service Center. There, the expended absorber granulates are collected and sorted in accordance with applicable local regulations for their classification and disposal. Where possible, the spent materials are re-processed for recovery of metals, or for other industrial uses.

Benefits
- Process application support
- Start-up support
- Installation support
- Service and maintenance
- Refill services

Before being recharged with fresh CLEANSORB granulate, the emptied columns are washed, thoroughly cleaned and dried. All sealing gaskets are replaced. The refilled columns are subjected to a strict quality control check-out procedure which includes helium leak-testing and packaging compatible with the customer’s grey area.

Consult your local CS CLEAN SYSTEMS partner for annual preventive maintenance contracts or waste gas analysis measurements.
CLEANSORB®
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CLEANSORB® BASELINE
As its name suggests, the BASELINE system offers an essential level of the components and functionality provided by the other models of the CLEANSORB product range. It is often the model of choice for research institutes or in pilot line or low-volume manufacturing.

CLEANSORB® LABLINE
The CLEANSORB LABLINE features a small absorber column in a compact, air-extracted cabinet.

The wide selectivity of CLEANSORB chemisorber media to a diverse list of gases and liquid precursors, ranging from corrosive or toxic species to latest-generation metalorganic complexes, offers ideal flexibility for R&D requirements.

A particular advantage for sporadic laboratory work is the passive operating principle. The LABLINE is always ready and does not have to be switched on, heated up or otherwise activated each time a new experiment is to be run.

CLEANSORB® FABLINE
FABLINE is the standard CLEANSORB model for waste gas removal on factory-scale applications. Available in three column sizes, the system is readily adaptable to the requirements of both pilot line and full-scale manufacturing. Drawing on 30 years experience and several thousand installations worldwide, the CLEANSORB product line has established an enviable reputation for solid engineering and reliability – even under the most demanding of process conditions. The FABLINE is constructed from corrosion-resistant 316L stainless steel and high quality, trustworthy components. Enabled by the built-in safety and efficiency of CS CLEAN SYSTEMS proprietary CLEANSORB® chemisorber media, FABLINE is the model of choice for a wide range of process applications including: Plasma Etching, CVD, ALD, Ion Implantation and CIGS Photovoltaics.

CLEANSORB® PRIMELINE
The PRIMELINE series, comprising the PS and PD model platforms, is described on the following pages.
Every single hour of process time lost to exhaust and scrubber maintenance can add thousands of dollars to product manufacturing costs. The CLEANSORB PRIMELINE series brings unsurpassed cost-of-ownership to high volume manufacturing.

On most installations, operator intervention is only required every few months. A key enabler for uptime is the minimized time required for column change. The smaller-footprint CLEANSORB PS model features a back-up column, allowing production to be run to completion even after the capacity of the main absorber column has become depleted. The larger CLEANSORB PD model incorporates two full-size absorber columns plus a back-up column; one column can remain active absorbing exhaust gas with full SEMI S2-compliant safety protection, while the second column is independently purged before removal from the cabinet for refilling.

The PRIMELINE series represents the fully-featured safety version of the CLEANSORB family. In the event of a loss of facilities, the system will revert to a safe state with redundant absorption capability. The system is specially engineered to handle safety-critical applications such as Metal Organic Chemical Vapor Deposition.

When configured for hydride gas processes such as MOCVD, unique control functions include an infra-red array for contactless temperature monitoring of the absorber columns, as well as an inert gas cooling mechanism. A dedicated class of CLEANSORB chemisorber media ensures highly effective, temperature-managed removal of toxics such as arsine or phosphine.

In both models, the individual columns are independently monitored for gas breakthrough. Automated routines for in-situ leak-testing and inert gas purging enhance safety and ease of operation. Further attributes of the PRIMELINE PD model are its touch screen, event and data logging, independent safety PLC, and SIL-certified components.
CLEAN-PROTECT

Safeguard against emergency gas escape. Uncontrolled release from gas cylinders poses a serious threat to environment and safety, owing to the high quantity of pressurized gas usually present in concentrated form. Gas leakages are known to have occurred: during storage of fresh cylinders; due to improper connection of fittings in gas cabinets; component failure, e.g. rupture of pressure regulator diaphragm; during storage of empty cylinders.

The purpose of the CLEAN-PROTECT is to absorb toxic or otherwise hazardous gases during a gas release incident. Escaping gases undergo an irreversible chemical reaction (oxidation or neutralization) within the CLEAN-PROTECT absorber bed, where they are safely converted into solid by-products. The system is installed in line with downstream air extract ducting and does not require power or other facilities to operate, meaning that it is permanently on 24/7 stand-by.

The unit is applicable to a wide range of hazardous gases, including: AsH3, BF3, Br2, CIF3, COCl2, F2, HCl, HF, HBr, H2S, H2Se, HCN, NH3, N2H4, PH3, SO2.

If no gas release incident occurs, the change-out frequency of the absorber bed is five years.

Benefits
- High flow rates. Up to 3600m3/h
- Absorption of toxic gas cylinder release
- Low pressure drop
- Permanently online
- Suitable for multi-cabinet installations
- Passive operating principle
- Applicable to a wide range of hazardous Gases

CLEANVENT

Mini Cartridge for Gas Cabinet Vent Lines
Before a new gas cylinder is put on-line within a gas supply cabinet, process gas remaining from the previous cylinder must first be removed – both for reasons of safety and to ensure integrity of the gas supply. The dead volume of residual gas is likely to be highly concentrated, toxic, pyrophoric, or corrosive.

For almost 30 years the CLEANVENT cartridge has proven itself a safe solution for the removal of hazardous purge gases. Installed within the gas cabinet on the suction side of the venturi vacuum generator, or in a valve manifold box, the CLEANVENT cartridge allows residual gases to be scrubbed “at-source”.

Refillable CLEANVENT cartridge types are available for a broad range of specialty gases and are supported by our worldwide network of service partners.

Benefits
- At-source removal of purge gases
- Gas cabinet installation
- Applicable to a wide range of hazardous gases

CLEANVENT CV10ST
Thermal Dry Bed Absorber for NF3 Removal
Designed for the removal of purge gases which are chemically stable at room temperature, the CLEANVENT CV10ST features a heated cartridge with control and monitoring elements in an air-extracted cabinet. The CV10ST is most commonly used for the removal of nitrogen trifluoride – a chemically stable gas used in the plasma cleaning of CVD chambers in semiconductor and photovoltaic manufacturing. Despite its stability, NF3 is a greenhouse gas with a high global warming potential.

The CV10ST is installed downstream of the gas supply cabinet or bulk gas supply manifold.
Abatement of global warming PFC gases
Most semiconductor manufacturers already implement measures to combat global warming emissions, with abatement of perfluorinated compounds (PFC) forming a key part of an overall reduction strategy. PFC gases such as CF4, CHF3, SF6 and NF3 are emitted from semiconductor Plasma Etch and Strip processes as well as from CVD Chamber Cleans.

The PCS PIRANHA uses microwave plasma energy to convert the stable PFCs to reactive by-products which are easily removed using a downstream scrubber such as a CLEANSORB FABLINE.

Hook it Up and Switch it On
The PCS PIRANHA does not require expensive facilities such as fuel lines, a DI water supply, or a waste water drain, and is also very economical in terms of fab footprint.

The optional Control and Interface Box (CIB2000) acts as a signal interface to the etcher tool and allows push-button selection and display of all important process parameters. The CIB2000 and High Voltage Supply (HVS2000) boxes are usually housed as a pair – typically mounted on the cabinet roof of a CLEANSORB system, or in a separate rack cabinet for an etch tool with multiple chambers.

Minimal Environmental Impact
PFC flows are abated in the vacuum foreline, before they are mixed with the pump’s nitrogen supply. This ensures maximum conversion efficiency with minimum energy wastage. Additional CO2-generating fuels are not required. Individual microwave power levels can be set for etch recipes having both high and low PFC flows. As a further energy-saving benefit: the PIRANHA is interlocked with the process to be switched on only when PFC gases are active.

Benefits
- High performance microwave power source
- Easily retrofitted to existing etch tool installations
- High conversion efficiency prior to pump dilution
- Energy and water efficient: environment-friendly
- Improved fab safety with no flames or fuel usage
**APPLICATION LIST**

**Speciality process gases and liquid precursors used in wafer processing, solar and MEMS manufacturing are likely to be either pyrophoric, toxic, or corrosive.**

### Process Application | Typical Gases or Liquid Precursors Used

#### Plasma Etch
- **Metal Etch**: Cl₂, Br₂, I₂, HCl, CF₄, SF₆, O₃, NO₂, NO, NH₃, PtCl₆
- **Poly Silicon Etch**: Cl₂, Br₂, HBr, SiCl₄, CF₄, NF₃, C₂F₆, C₃F₈
- **Nitride Etch, Oxide Etch**: CF₃, CHF₃, C₂F₆, C₃F₈, CH₂F₂, NF₃, SF₆, NO₂, SF₅Cl, NO, NF₃
- **Tungsten Etchback**: SF₆, O₃

#### Ion Implantation
- High, Medium, Low: AsH₃, PH₃, B₂H₆, P, As, Sb, Sn(CH₃)₂, GeH₄, GeF₄

#### ALD, LPCVD, PECVD, HDP-CVD
- **TEOS, undoped**: TEOS, O₂, H₂O
- **BF₅Si**: TEOS, O₂, SiH₄, SiH₂Cl₂, SiH₂Cl₃, SiH₂Br₂, SiH₂Br₃
- **Poly-Si (doped)**: SiH₄, (AsH₃, PH₃)
- **Silicon Germanium**: SiH₄, GeH₄, Ge₂H₆
- **Oxide**: SiH₄, O₂, NH₃
- **Nitride, doped**: SiH₄, NH₃, (SiH₂Cl₂, SiH₂Cl₃, SiH₂Br₂, SiH₂Br₃)
- **Low-k dielectrics**: 1MS, 2MS, 3MS, 4MS, DMDMOS
- **High-k dielectrics**: TMA, TEMAH, TDEAH, TAETO, PET
- **Gate Electrodes**: MPA, Ru(Et)₂, PEoMAT
- **Copper CVD**: Cu(hfac)₂(TMS)
- **Tungsten (Silicide)**: W(II), SiH₂Cl₂, SiH₂Br₂, SiH₂Cl₃, SiH₂Br₃
- **Barrier Layers**: Si₃N₄, SiO₂, Si₃N₄/SiO₂, Si₃N₄/SiO₂, Si₃N₄/SiO₂, Si₃N₄/SiO₂, Si₃N₄/SiO₂

#### Plasma Chamber Cleaning
- **PFC plasma**: C₃F₆, C₂F₆, NF₃, Ar, H₂, He
- **Remote NF3 plasma**: F₂, Ar, Kr, He, N₂, Ar, Kr, He, N₂

#### Epitaxy
- **Silicon (doped)**: DCS, TCS, SiH₄, (AsH₃, PH₃, B₂H₆)
- **Silicon-Germanium**: SiH₄, GeH₄, (AsH₃, PH₃, B₂H₆)
- **Silicon-Carbide (SiC)**: SiH₄, CH₄, C₃H₄, C₂H₂, Ar, He, N₂

#### Compound Semiconductors, Optoelectronics, III-V on Si
- GaAs, InP MOVPE (MOCVD): TMGa, AsH₃, TBA, TMIn, P, AsH₃, PH₃
- GaN MOVPE (MOCVD): TMGa, NH₃, UDMH
- MBE (MOMBE): As, P, AsH₃, PH₃, P, AsH₃, PH₃
- III-V Etch: Cl₂, Br₂, I₂, HBr, SiCl₄, SiF₄, CH₂Cl₂, GaCl₃, InCl₃, AsH₃, H₂, O₂

#### Photovoltaics
- **Concentrator Photovoltaics**: PH₃, AsH₃, metalorganics, SiH₄, GeH₄, H₂S, H₂Se
- **CIGS**: PH₃, AsH₃, metalorganics, SiH₄, GeH₄

Consult us regarding the many process applications and gases not listed above.
FOR SUSTAINABLE MANUFACTURING

Safety and the Environment...

For CS CLEAN SYSTEMS, environmental protection is the essence of our business. Our eco-friendly CLEANSORB technology safely removes hazardous waste gases without consuming energy, water or fuel. One CLEANSORB column will typically have an absorbing lifetime of several months. During this time, several thousand liters of waste gases will be bound in a compact dry form. There are no secondary emissions to the environment in the form of waste water. All of our products are designed for lifetime serviceability and re-use.

Best Prepared for the Future...

The process technologies and precursor materials used for chip manufacture continue to diversify against the background of a maturing, globalized industry with increased emphasis on Cost-of-Ownership.

At the same time, growing environmental awareness is demanding more efficient usage of materials and a reduction in factory emissions. Proud of our reputation for innovative product design and high-quality engineering, CS CLEAN SYSTEMS is best prepared and fully committed to solving these exciting new challenges. We look forward to serving you in the coming years ahead.

Disclaimer

This brochure is intended as an introduction to our organization, products and services. While every effort has been made to ensure that the information given in this document is accurate, it is not a legal document nor a source of technical specifications. Responsibility cannot be accepted for any liability incurred or loss suffered as a consequence of relying on any matter published herein.

The reader should be aware that the configuration of a waste gas abatement system requires specialist consideration of the exhaust gases to be treated and the associated process conditions. CS CLEAN SYSTEMS or one of its authorized sales and service partners will be pleased to advise you regarding the specific waste gas treatment requirements of your process.
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